FAIRCHILD SEMICONDUCTOR®

March 20111

FSL126HR
Green Mode Fairchild Power Switch (FPS™)

Features

- Internal Avalanche-Rugged SenseFET (650V)
- Under 50mW Standby Power Consumption at $265V_{AC}$, No-load Condition with Burst Mode
- Precision Fixed Operating Frequency with Frequency Modulation for Attenuating EMI
- Internal Startup Circuit
- Built-in Soft-Start: 20ms
- Pulse-by-Pulse Current Limiting
- Various Protections: Over-Voltage Protection (OVP), Overload Protection (OLP), Output-Short Protection (OSP), Abnormal Over-Current Protection (AOCP), Internal Thermal Shutdown Function with Hysteresis (TSD)
- Auto-Restart Mode
- Under-Voltage Lockout (UVLO)
- Low Operating Current: 1.8mA
- Adjustable Peak Current Limit

Applications

- SMPS for VCR, STB, DVD, & DVCD Players
- SMPS for Home Appliance
- Adapter

Related Resources

- *AN-4137 — Design Guidelines for Off-line Flyback Converters using FPS™*
- *AN-4141 — Troubleshooting and Design Tips for Fairchild Power Switch (FPS™) Flyback Applications*
- *AN-4147 —-Design Guidelines for RCD Snubber of Flyback*

Description

The FSL126HR integrated Pulse Width Modulator (PWM) and SenseFET is specifically designed for high-performance offline Switch-Mode Power Supplies (SMPS) with minimal external components. FSL126HR includes integrated high-voltage power switching regulators that combine an avalanche-rugged SenseFET with a current-mode PWM control block.

The integrated PWM controller includes: Under-Voltage Lockout (UVLO) protection, Leading-Edge Blanking (LEB), a frequency generator for EMI attenuation, an optimized gate turn-on/turn-off driver, Thermal Shutdown (TSD) protection, and temperature-compensated precision current sources for loop compensation and fault protection circuitry. The FSL126HR offers good soft-start performance. When compared to a discrete MOSFET and controller or RCC switching converter solution, the FSL126HR reduces total component count, design size, and weight; while increasing efficiency, productivity, and system reliability. This device provides a basic platform that is well suited for the design of cost-effective flyback converters.

Maximum Output Power[1]			
$230V_{AC}$ ± 15%[2]		$85\text{-}265V_{AC}$	
Adapter[3]	Open Frame	Adapter[3]	Open Frame
15W	21W	12W	17W

Notes:
1. The junction temperature can limit the maximum output power.
2. $230V_{AC}$ or $100/115V_{AC}$ with doubler.
3. Typical continuous power in a non-ventilated enclosed adapter measured at 50°C ambient.

Ordering Information

Part Number	Operating Temperature Range	Top Mark	Package	Packing Method
FSL126HR	-40 to 105°C	FSL126HR	8-Lead, Dual Inline Package (DIP)	Rail

Typical Application Diagram

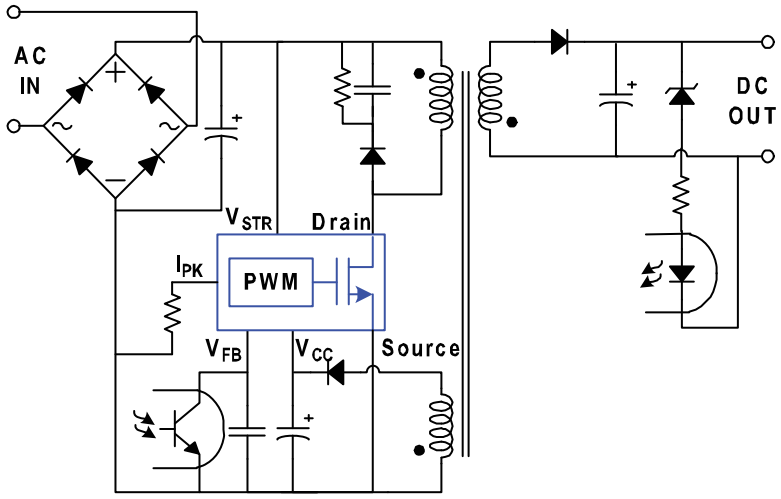


Figure 1. Typical Application

Internal Block Diagram

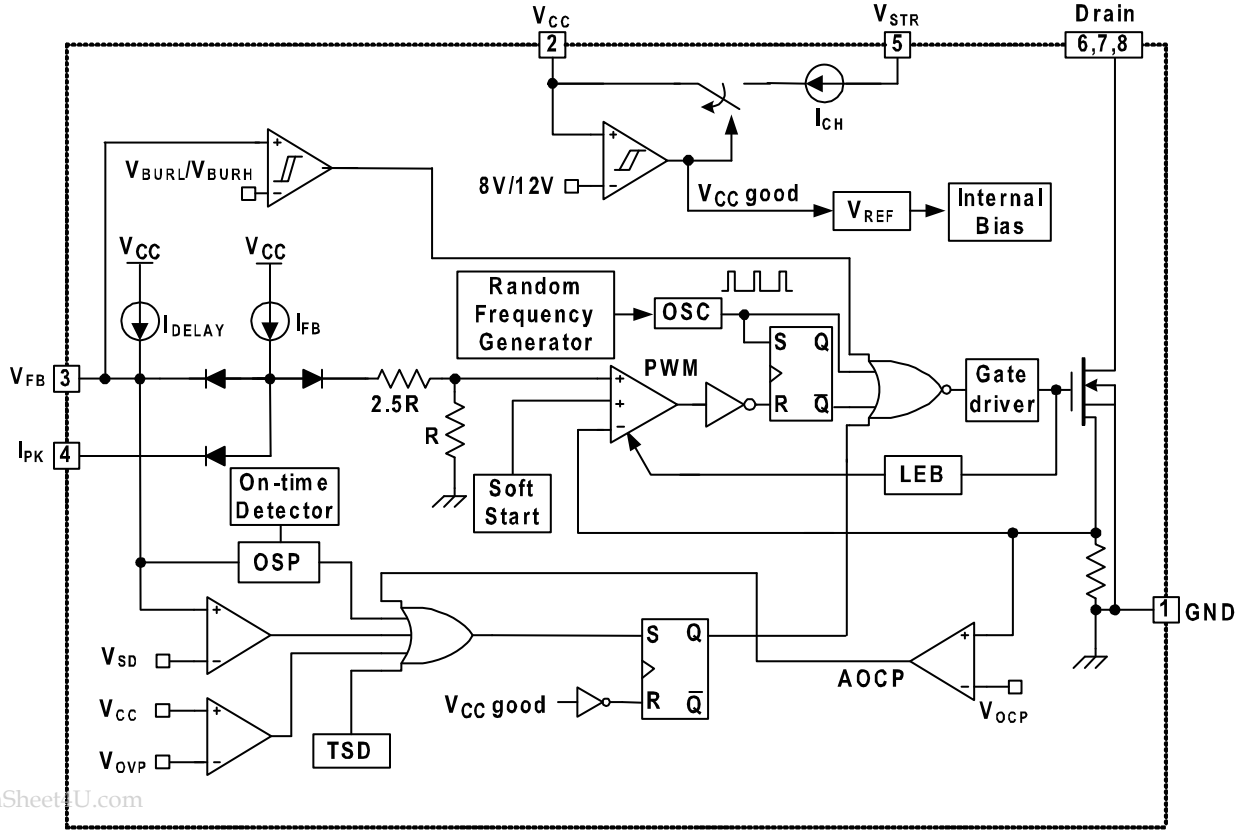


Figure 2. Internal Block Diagram

Pin Configuration

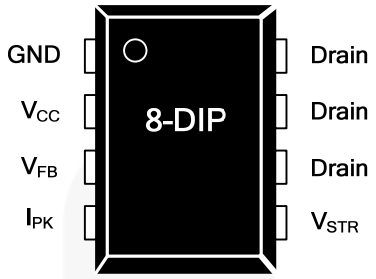


Figure 3. Pin Configuration

Pin Definitions

Pin #	Name	Description
1	GND	**Ground**. SenseFET source terminal on the primary side and internal control ground.
2	V_{CC}	**Positive Supply Voltage Input**. Although connected to an auxiliary transformer winding, current is supplied from pin 5 (V_{STR}) via an internal switch during startup (*see Figure 2*). Once V_{CC} reaches the UVLO upper threshold (12V), the internal startup switch opens and device power is supplied via the auxiliary transformer winding.
3	V_{FB}	**Feedback Voltage**. The non-inverting input to the PWM comparator, it has a 0.4mA current source connected internally, while a capacitor and opto-coupler are typically connected externally. There is a delay while charging external capacitor C_{FB} from 2.4V to 6V using an internal 5μA current source. This delay prevents false triggering under transient conditions, but still allows the protection mechanism to operate under true overload conditions.
4	I_{PK}	**Peak Current Limit**. Adjusts the peak current limit of the SenseFET. The feedback 0.4mA current source is diverted to the parallel combination of an internal 6kΩ resistor and any external resistor to GND on this pin to determine the peak current limit.
5	V_{STR}	**Startup**. Connected to the rectified AC line voltage source. At startup, the internal switch supplies internal bias and charges an external storage capacitor placed between the V_{CC} pin and ground. Once V_{CC} reaches 12V, the internal switch is opened.
6, 7, 8	Drain	**Drain**. Designed to connect directly to the primary lead of the transformer and capable of switching a maximum of 650V. Minimizing the length of the trace connecting these pins to the transformer decreases leakage inductance.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. T_J = 25°C, unless otherwise specified.

Symbol	Parameter	Min.	Max.	Unit
V_{STR}	V_{STR} Pin Voltage	-0.3	650.0	V
V_{DS}	Drain Pin Voltage	-0.3	650.0	V
V_{CC}	Supply Voltage		26	V
V_{FB}	Feedback Voltage Range	-0.3	12.0	V
I_D	Continuous Drain Current		2	A
I_{DM}	Drain Current Pulsed[4]		8	A
E_{AS}	Single Pulsed Avalanche Energy[5]		73	mJ
P_D	Total Power Dissipation		1.5	W
T_J	Operating Junction Temperature	Internally Limited		°C
T_A	Operating Ambient Temperature	-40	+105	°C
T_{STG}	Storage Temperature	-55	+150	°C
ESD	Human Body Model, JESD22-A114[6]	5		KV
	Charged Device Model, JESD22-C101[6]	2		
Θ_{JA}	Junction-to-Ambient Thermal Resistance[7,8]		80	°C/W
Θ_{JC}	Junction-to-Case Thermal Resistance[7,9]		19	°C/W
Θ_{JT}	Junction-to-Top Thermal Resistance[7,10]		33.7	°C/W

Notes:

4. Repetitive rating: pulse width limited by maximum junction temperature.
5. L=30mH, starting T_J=25°C.
6. Meets JEDEC standards JESD 22-A114 and JESD 22-C101.
7. All items are tested with the standards JESD 51-2 and JESD 51-10.
8. Θ_{JA} free-standing, with no heat-sink, under natural convection.
9. Θ_{JC} junction-to-lead thermal characteristics under Θ_{JA} test condition. T_C is measured on the source #7 pin closed to plastic interface for Θ_{JA} thermo-couple mounted on soldering.
10. Θ_{JT} junction-to-top of thermal characteristic under Θ_{JA} test condition. T_t is measured on top of package. Thermo-couple is mounted in epoxy glue.

Electrical Characteristics

T_A = 25°C unless otherwise specified.

Symbol	Parameter		Conditions	Min.	Typ.	Max.	Units
SenseFET Section							
BV_{DSS}	Drain-Source Breakdown Voltage		V_{CC} = 0V, I_D = 250μA	650			V
I_{DSS}	Zero Gate Voltage Drain Current		V_{DS} = 650V, V_{GS} = 0V			250	μA
$R_{DS(ON)}$	Drain-Source On-State Resistance		V_{GS} = 10V, V_{GS} = 0V, T_C = 25°C		4.9	6.2	Ω
C_{ISS}	Input Capacitance		V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		210		pF
C_{OSS}	Output Capacitance		V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		33.3		pF
C_{RSS}	Reverse Transfer Capacitance		V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		4.1		pF
$t_{d(ON)}$	Turn-On Delay		V_{DD} = 350V, I_D = 2A		23		ns
t_r	Rise Time		V_{DD} = 350V, I_D = 2A		16.4		ns
$t_{d(OFF)}$	Turn-Off Delay		V_{DD} = 350V, I_D = 2A		17.2		ns
t_f	Fall Time		V_{DD} = 350V, I_D = 2A		23		ns
Control Section							
f_{OSC}	Switching Frequency		V_{DS} = 650V, V_{GS} = 0V	90	100	110	KHz
Δf_{OSC}	Switching Frequency Variation		V_{GS} = 10V, V_{GS} = 0V, T_C = 125°C		±5	±10	%
f_{FM}	Frequency Modulation				±3		KHz
D_{MAX}	Maximum Duty Cycle		V_{FB} = 4V	71	77	83	%
D_{MIN}	Minimum Duty Cycle		V_{FB} = 0V	0	0	0	%
V_{START}	UVLO Threshold Voltage			11	12	13	V
V_{STOP}			After Turn-On	7	8	9	V
I_{FB}	Feedback Source Current		V_{FB} = 0V	320	400	480	μA
$t_{S/S}$	Internal Soft-Start Time		V_{FB} = 4V	15	20	25	ms
Burst Mode Section							
V_{BURH}	Burst Mode Voltage		T_J = 25°C	0.48	0.60	0.72	V
V_{BURL}				0.32	0.45	0.58	V
$V_{BUR(HYS)}$					150		mV
Protection Section							
I_{LIM}	Peak Current Limit		T_J = 25°C, di/dt = 300mA/μs	1.32	1.50	1.68	A
t_{CLD}	Current Limit Delay Time[11]			200			ns
V_{SD}	Shutdown Feedback Voltage		V_{CC} = 15V	5.5	6.0	6.5	V
I_{DELAY}	Shutdown Delay Current		V_{FB} = 5V	3.5	5.0	6.5	μA
V_{OVP}	Over-Voltage Protection Threshold		V_{FB} = 2V	22.5	24.0	25.5	V
t_{OSP}	Output-Short Protection[11]	Threshold Time	T_J = 25°C OSP Triggered When t_{ON}<t_{OSP}, V_{FB}>V_{OSP} and Lasts Longer than t_{OSP_FB}		1.00	1.35	μs
V_{OSP}		Threshold Feedback Voltage		1.44	1.60		V
t_{OSP_FB}		Feedback Blanking Time		2.0	2.5		μs
V_{AOCP}	AOCP Voltage[11]		T_J = 25°C	0.85	1.00	1.15	V
TSD	Thermal Shutdown[11]	Shutdown Temperature		125	137	150	°C
HYS_{TSD}		Hysteresis			60		°C
t_{LEB}	Leading-Edge Blanking Time[11]			300			ns

Continued on the following page…

Electrical Characteristics (Continued)

T_A = 25°C unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
Total Device Section						
I_{OP1}	Operating Supply Current(11) (While Switching)	V_{CC} = 14V, V_{FB} > V_{BURH}		2.5	3.5	mA
I_{OP2}	Operating Supply Current (Control Part Only)	V_{CC} = 14V, V_{FB} < V_{BURL}		1.8	2.5	mA
I_{CH}	Startup Charging Current	V_{CC} = 0V	0.9	1.1	1.3	mA
V_{STR}	Minimum V_{STR} Supply Voltage	V_{CC} = V_{FB} = 0V, V_{STR} Increase	35			V

Note:

11. Though guaranteed by design, it is not 100% tested in production.

Typical Performance Characteristics

These characteristic graphs are normalized at T_A=25.

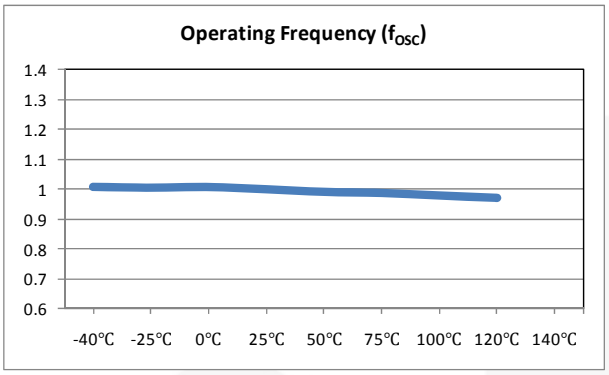


Figure 4. Operating Frequency vs. Temperature

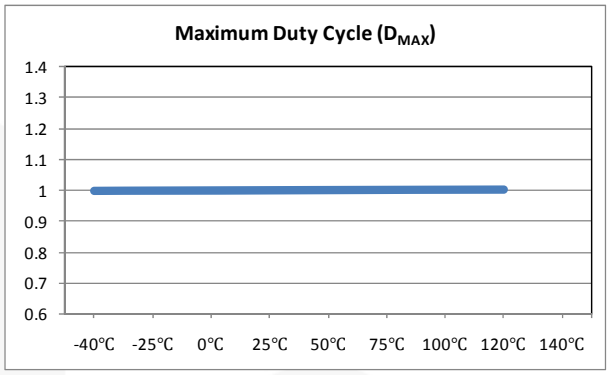


Figure 5. Maximum Duty Cycle vs. Temperature

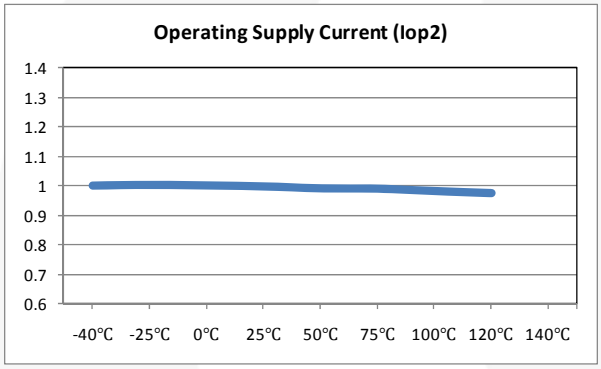


Figure 6. Operating Supply Current vs. Temperature

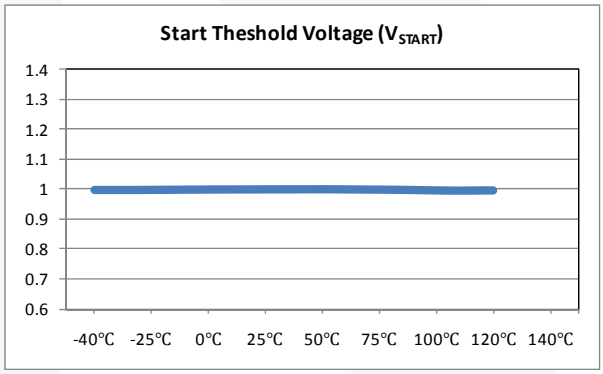


Figure 7. Start Threshold Voltage vs. Temperature

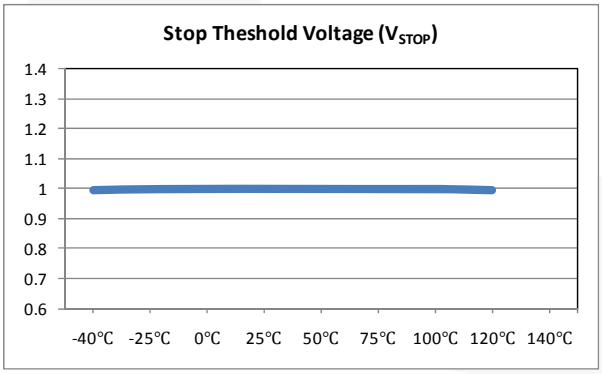


Figure 8. Stop Threshold Voltage vs. Temperature

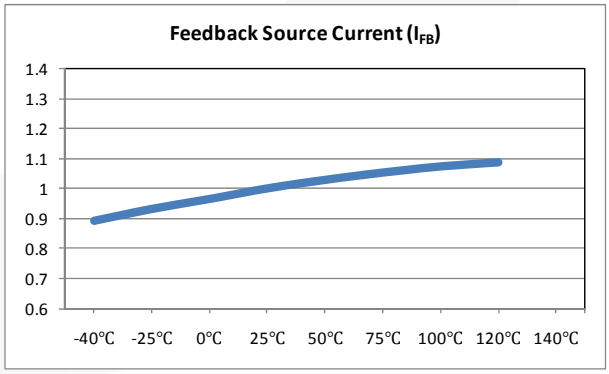


Figure 9. Feedback Source Current vs. Temperature

Typical Performance Characteristics (Continued)

These characteristic graphs are normalized at T_A=25.

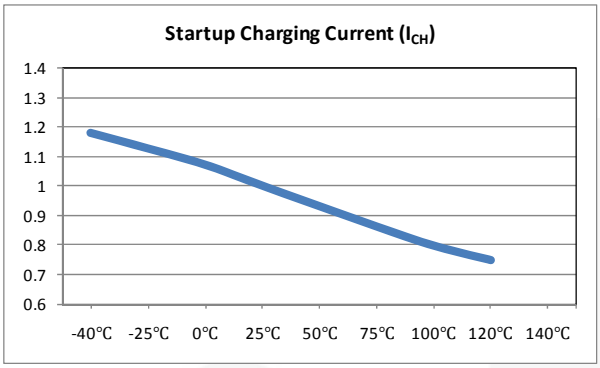


Figure 10. Startup Charging Current vs. Temperature

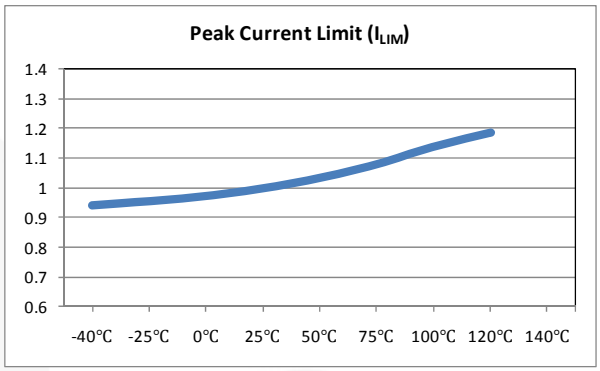


Figure 11. Peak Current Limit vs. Temperature

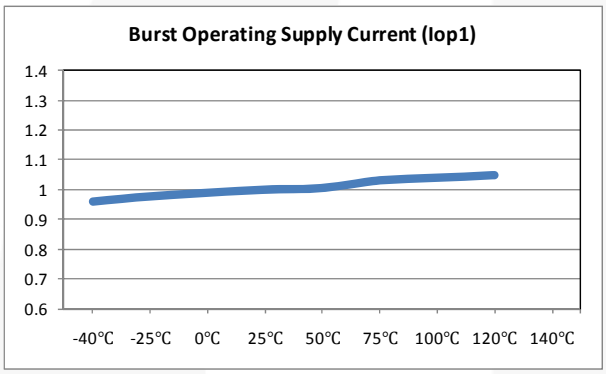


Figure 12. Burst Operating Supply Current vs. Temperature

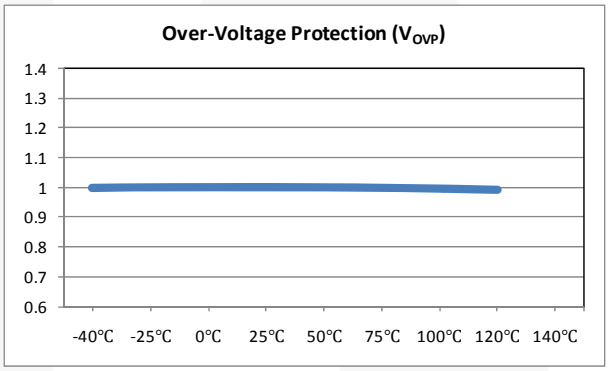


Figure 13. Over-Voltage Protection vs. Temperature

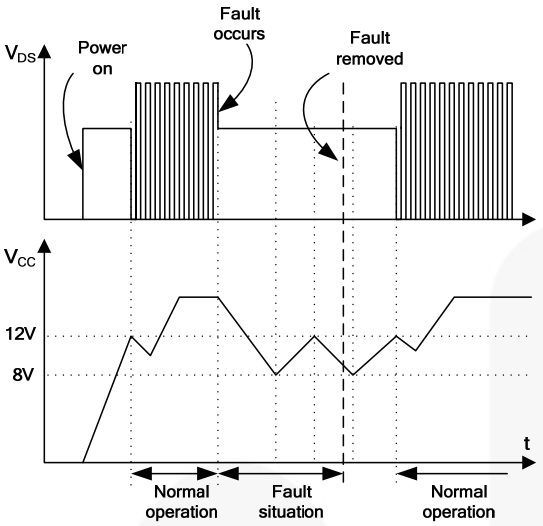


Figure 17. Auto-Restart Protection Waveforms

Overload Protection (OLP)

Overload is defined as the load current exceeding a pre-set level due to an unexpected event. In this situation, the protection circuit should be activated to protect the SMPS. However, even when the SMPS is operating normally, the overload protection (OLP) circuit can be activated during the load transition or startup. To avoid this undesired operation, the OLP circuit is designed to be activated after a specified time to determine whether it is a transient situation or a true overload situation.

In conjunction with the I_{PK} current limit pin (if used), the current-mode feedback path limits the current in the SenseFET when the maximum PWM duty cycle is attained. If the output consumes more than this maximum power, the output voltage (V_O) decreases below its rating voltage. This reduces the current through the opto-coupler LED, which also reduces the opto-coupler transistor current, thus increasing the feedback voltage (V_{FB}). If V_{FB} exceeds 2.4V, the feedback input diode is blocked and the 5μA current source (I_{DELAY}) starts to charge C_{FB} slowly up to V_{CC}. In this condition, V_{FB} increases until it reaches 6V, when the switching operation is terminated, as shown in Figure 18. The shutdown delay is the time required to charge C_{FB} from 2.4V to 6V with 5μA current source.

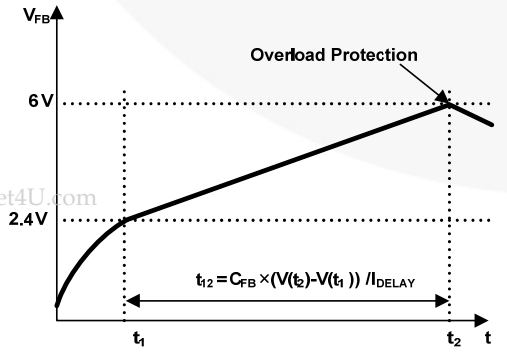


Figure 18. Overload Protection (OLP)

Abnormal Over-Current Protection (AOCP)

When the secondary rectifier diodes or the transformer pin are shorted, a steep current with extremely high di/dt can flow through the SenseFET during the LEB time. Even though the FPS has OLP (Overload Protection), it is not enough to protect the FPS in that abnormal case, since severe current stress is imposed on the SenseFET until OLP triggers. The FPS includes the internal AOCP (Abnormal Over-Current Protection) circuit shown in Figure 19. When the gate turn-on signal is applied to the power SenseFET, the AOCP block is enabled and monitors the current through the sensing resistor. The voltage across the resistor is compared with a preset AOCP level. If the sensing resistor voltage is greater than the AOCP level, the set signal is applied to the latch, resulting in the shutdown of the SMPS.

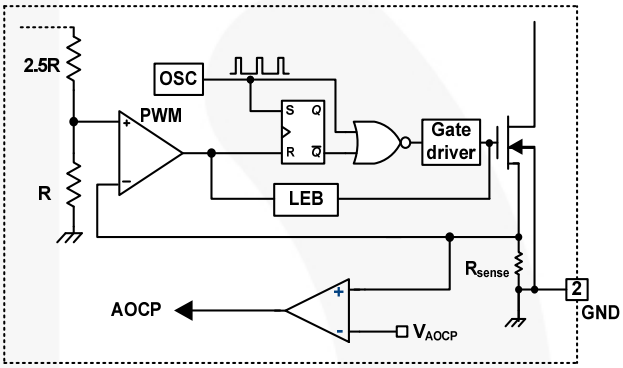


Figure 19. Abnormal Over-Current Protection

Thermal Shutdown (TSD)

The SenseFET and the control IC are integrated, making it easier to detect the temperature of the SenseFET. When the temperature exceeds approximately 137°C, thermal shutdown is activated.

Over-Voltage Protection (OVP)

In the event of a malfunction in the secondary-side feedback circuit or an open feedback loop caused by a soldering defect, the current through the opto-coupler transistor becomes almost zero. Then, V_{FB} climbs up in a similar manner to the overload situation, forcing the preset maximum current to be supplied to the SMPS until the overload protection is activated. Because excess energy is provided to the output, the output voltage may exceed the rated voltage before the overload protection is activated, resulting in the breakdown of the devices in the secondary side. To prevent this situation, an over-voltage protection (OVP) circuit is employed. In general, V_{CC} is proportional to the output voltage and the FPS uses V_{CC} instead of directly monitoring the output voltage. If V_{CC} exceeds 24V, OVP circuit is activated, resulting in termination of the switching operation. To avoid undesired activation of OVP during normal operation, V_{CC} should be designed to be below 24V.

Output-Short Protection (OSP)

If the output is shorted, steep current with extremely high di/dt can flow through the SenseFET during the LEB time. Such a steep current brings high-voltage stress on the drain of SenseFET when turned off. To protect the device from such an abnormal condition, OSP detects V_{FB} and SenseFET turn-on time. When the V_{FB} is higher than 1.6V and the SenseFET turn-on time is lower than 1.2μs, the FPS recognizes this condition as an abnormal error and shuts down PWM switching until V_{CC} reaches V_{START} again. An abnormal condition output is shown in Figure 20.

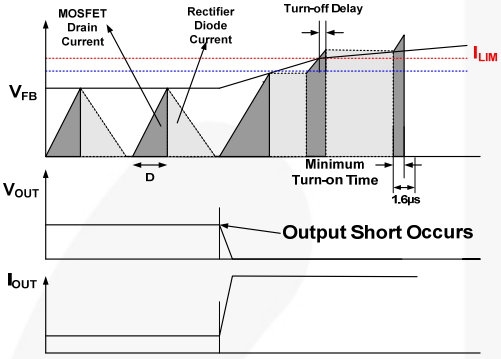


Figure 20. Output Short Waveforms (OSP)

Soft-Start

The FPS has an internal soft-start circuit that slowly increases the feedback voltage, together with the SenseFET current, after it starts. The typical soft-start time is 20ms, as shown in Figure 21, where progressive increments of the SenseFET current are allowed during the startup phase. The pulse width to the power switching device is progressively increased to establish the correct working conditions for transformers, inductors, and capacitors. The voltage on the output capacitors is progressively increased with the intention of smoothly establishing the required output voltage. Soft-start helps to prevent transformer saturation and reduce the stress on the secondary diode.

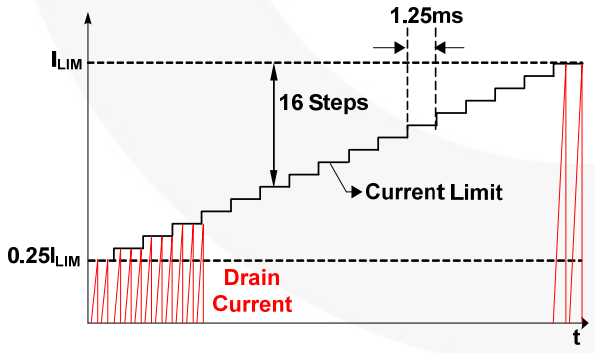


Figure 21. Internal Soft-Start

Burst Operation

To minimize power dissipation in standby mode, the FPS enters burst mode. As the load decreases, the feedback voltage decreases. As shown in Figure 22, the device automatically enters burst mode when the feedback voltage drops below V_{BURH}.

Switching continues until the feedback voltage drops below V_{BURL}. At this point, switching stops and the output voltages start to drop at a rate dependent on the standby current load. This causes the feedback voltage to rise. Once it passes V_{BURH}, switching resumes. The feedback voltage then falls and the process repeats. Burst mode alternately enables and disables switching of the SenseFET and reduces switching loss in standby mode.

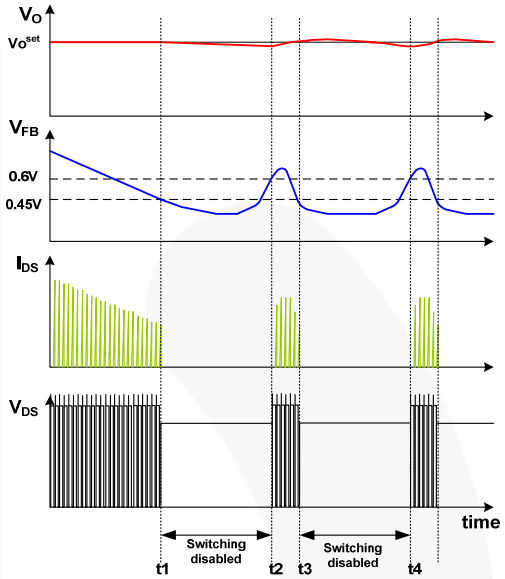


Figure 22. Burst-Mode Operation

Adjusting Peak Current Limit

As shown in Figure 23, a combined 6kΩ internal resistance is connected to the non-inverting lead on the PWM comparator. An external resistance of Rx on the current limit pin forms a parallel resistance with the 6kΩ when the internal diodes are biased by the main current source of 400μA. For example, FSL126HR has a typical SenseFET peak current limit (I_{LIM}) of 1.5A. I_{LIM} can be adjusted to 1A by inserting Rx between the I_{PK} pin and the ground. The value of the Rx can be estimated by the following equations:

$$1.5A:1A = 6k\Omega:Xk\Omega \quad (1)$$

$$X = Rx \parallel 6k\Omega \quad (2)$$

where X is the resistance of the parallel network.

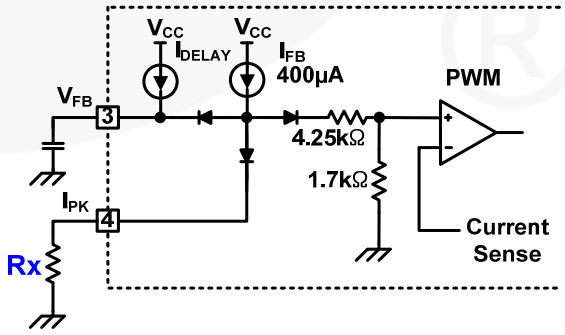
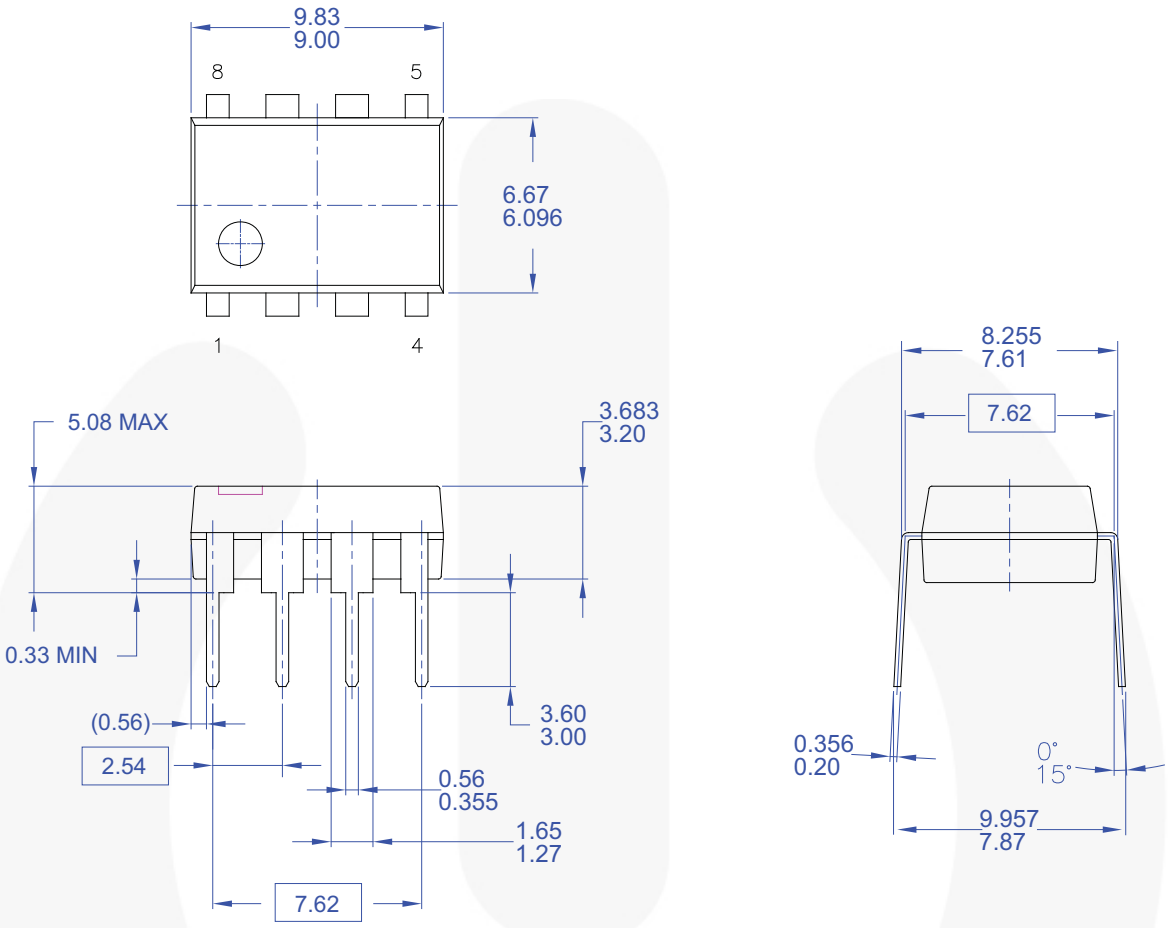


Figure 23. Peak Current Limit Adjustment

Physical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

A) THIS PACKAGE CONFORMS TO JEDEC MS-001 VARIATION BA

B) ALL DIMENSIONS ARE IN MILLIMETERS.

C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

D) DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994

E) DRAWING FILENAME AND REVSION: MKT-N08FREV2.

Figure 24. 8-Lead, Dual Inline Package (DIP)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

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EfficientMax™
ESBC™
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Fairchild Semiconductor®
FACT Quiet Series™
FACT®
FAST®
FastvCore™
FETBench™
FlashWriter®*
FPS™
F-PFS™
FRFET®
Global Power Resource℠
Green FPS™
Green FPS™ e-Series™
Gmax™
GTO™
IntelliMAX™
ISOPLANAR™
MegaBuck™
MICROCOUPLER™
MicroFET™
MicroPak™
MicroPak2™
MillerDrive™
MotionMax™
Motion-SPM™
mWSaver™
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OPTOLOGIC®
OPTOPLANAR®
PDP SPM™
Power-SPM™
PowerTrench®
PowerXS™
Programmable Active Droop™
QFET®
QS™
Quiet Series™
RapidConfigure™
Saving our world, 1mW/W/kW at a time™
SignalWise™
SmartMax™
SMART START™
SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS®
SyncFET™
Sync-Lock™
SYSTEM GENERAL®*
The Power Franchise®
The Right Technology for Your Success™
the power franchise
TinyBoost™
TinyBuck™
TinyCalc™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
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Definition of Terms

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